

Ranger3 3D vision camera for inline inspection HIGH-PERFORMANCE 3D INSPECTION IN THE ELECTRONICS INDUSTRY



High resolution at exceptional speed

AUTOMATIC OPTICAL INSPECTION (AOI) WITH RANGER3

High resolution

- CMOS sensor from SICK with ROCC technology for reliable 3D performance
- Sensor resolution
 2,560 x 832 pixels
- Resolution of the Z-axis of up to 0.3 µm

Flexible use

- Reliable and accurate measurements on dark and light surfaces
- 3D, reflective, and scattered light measurement in one device
- Individually adjustable camera settings

Increased throughput

• 3D measuring speed up to 46 kHz



Customized AOI inspection solution

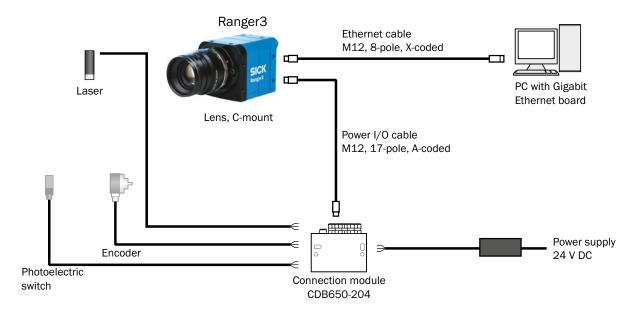
 Option of integrating customized inspection solutions by configuring geometry and working distance

Simple integration

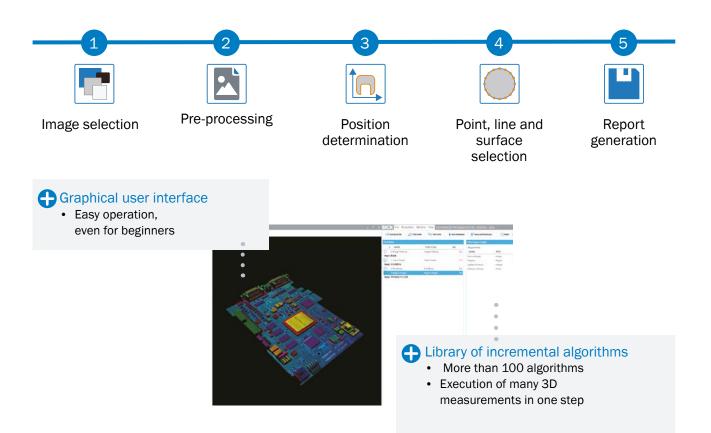
- Complete with accessories and software package for quick and easy installation
- Stream setup software available for easy setup of two cameras with laser
- Software integration based on the GigE Vision and GenlCam standards

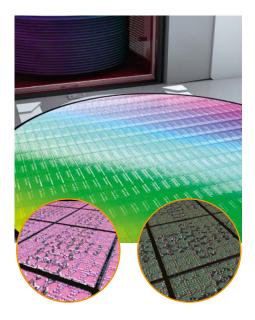


MOUNTING AND CONFIGURATION



5 EASY STEPS TO HEIGHT MEASUREMENT



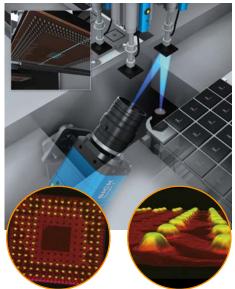


Surface inspection of wafers after etching

- Measurement of surface roughness of semiconductors
- Suitable for very small structures in the range of 10 μm

Measurement accuracy

- Resolution in X/Y-direction: 5 μm
- Resolution in Z-direction: 0.5 µm
- Measuring speed: 150 mm/s
- Laser selection:
 660 nm, 50 mW, high performance
 450 nm, 30 mW, mid-range performance

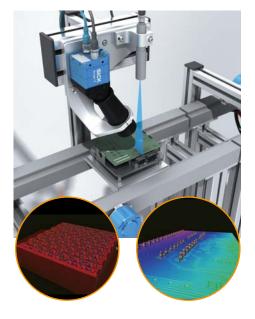


Coplanarity testing of ball grid arrays (BGAs)

- · Testing of coplanarity and correct position of the ball grid arrays in one step
- Suitable for solder beads with a height of 30 μm to 600 μm

Measurement accuracy

- Resolution in X/Y-direction: 5 μm
- Resolution in Z-direction: 0.5 µm
- Measuring speed: 150 mm/s
- Laser selection:
 - 405 nm, 120 mW, high performance 450 nm, 60 mW, mid-range performance

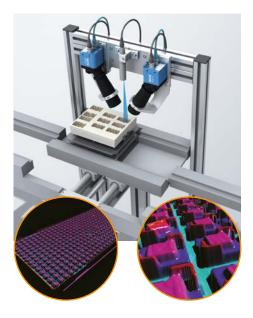


Pin inspection

- · Testing for presence, coplanarity and correct alignment of pins in one step
- · Suitable for industrial, network and vehicle plug connectors
- · Can be individually configured for different fields of view

Measurement accuracy

- Resolution in X/Y-direction: 10 µm
- Resolution in Z-direction: 1 μm
- Measuring speed: 300 mm/s
- Laser selection:
 405 nm, 30 mW, low performance
 450 nm, 60 mW, mid-range performance

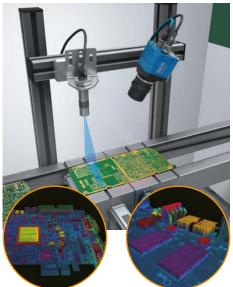


Inspection of tray stacks

- Checking of tray stack dimensions and semiconductor testing in one step
- Suitable for IC trays and plug connector trays
- Freely adjustable field of view of 10 cm, 15 cm or 20 cm

Measurement accuracy

- Resolution in X/Y-direction: 95 μm
- Resolution in Z-direction: 10 µm
- Measuring speed: 500 mm/s
- Laser selection: 405 nm, 120 mW, high performance 450 nm, 60 mW, mid-range performance



Inspection of printed circuit board components

- Inspection of various components in one step before and after populating the printed circuit board
- Determination of pin height, resistor position and capacitor position in one step

Measurement accuracy

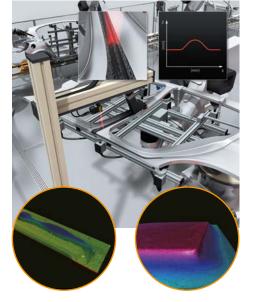
- Resolution in X/Y-direction: 20 µm
- Resolution in Z-direction: 2 µm
- Measuring speed: 60 mm/s
- Laser selection:
 - 405 nm, 120 mW, high performance
 - 450 nm, 60 mW, mid-range performance

Inspection of adhesive application

- Testing for presence of adhesive and quality of application
- Individually adjustable geometry

Measurement accuracy

- Resolution in X/Y-direction: 30 µm
- Resolution in Z-direction: 5 μm
- Measuring speed: 500 mm/s
- Laser selection:
 405 nm, 120 mW, high performance
 450 nm, 60 mW, mid-range performance



A NEW STANDARD FOR HIGH SPEED 3D

